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(54) Title: METHODS FOR PLANARIZATION OF GROUP VIII METAL-CONTAINING SURFACES USING A FIXED ABRASIVE ARTICLE

(57) Abstract: A planarization method includes providing a Group VIII metal-containing surface (preferably, a platinum-containing surface) and positioning it for contact with a fixed abrasive article in the presence of a planarization composition, wherein the fixed abrasive article comprises a plurality of abrasive particles having a hardness of no greater than about 6.5 Mohs dispersed within a binder adhered to at least one surface of a backing material.



WO 03/059571 A1